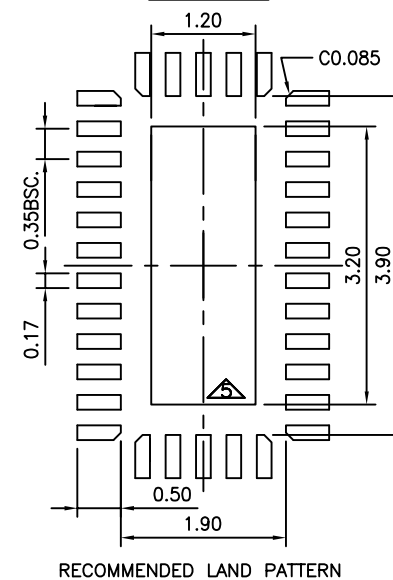
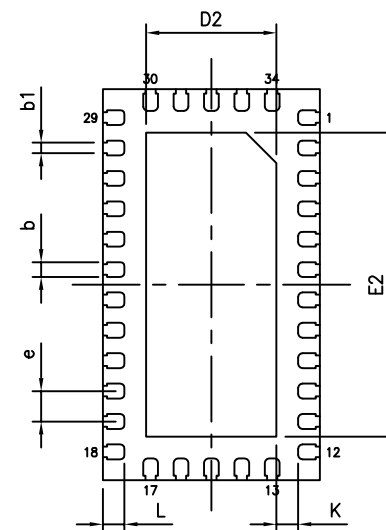
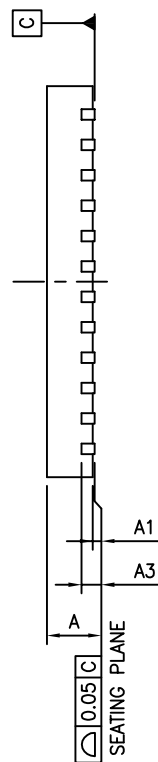


SYMBOLS	MIN.	NOM.	MAX.
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A3	0.150 REF.		
b	0.12	0.17	0.22
b1	0.07	0.12	0.17
D	2.40	2.50	2.60
E	4.40	4.50	4.60
e	0.35 BSC		
L	0.20	0.25	0.30
K	0.20	—	—
D2	1.45	1.50	1.55
E2	3.45	3.50	3.55



NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-288
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA (MESH STENCIL DESIGN IS RECOMMENDED).



PERICOM
A PRODUCT LINE OF DIODES INCORPORATED
ENABLING SERIAL CONNECTIVITY

DATE: 06/07/21

DESCRIPTION: 34-Contact, Ultra Thin Quad Flat No-Lead (UQFN), U-QFN2545-34

PACKAGE CODE: ZTF (ZTF34)

DOCUMENT CONTROL #: PD-2230

REVISION: B